

Sir:

Transmitted herewith for filing is the Patent Application of:

Inventor: **AN-CHUN TU, CHEN-MING HUANG**

19270 U.S.PTO
10/700779
110403

For: **METHOD FOR IMPROVING INTERLEVEL DIELECTRIC GAP FILLING OVER SEMICONDUCTOR STRUCTURES**

HAVING HIGH ASPECT RATIOS

Enclosed are:

2 sheets of drawing(s) - formal.

An assignment of the invention to **Taiwan Semiconductor Manufacturing Co.**

An associate power of attorney Applicant claims small entity status

Request & Certification under 35 USC 122(b)(2)(b)(i)

The filing fee has been calculated as shown below:

	(Col. 1)	(Col. 2)	OTHER THAN A SMALL ENTITY	
FOR:	NO. FILED	NO. EXTRA	RATE	FEE
BASIC FEE				\$ 770.
TOTAL CLAIMS	26 -20=	6	x 18 =	\$ 108.
INDEP CLAIMS	2 -3=	0	x 86 =	\$ 0.
		SUB TOTAL		\$ 878.
		ASSIGNMENT		\$40.
		TOTAL		\$ 918.

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Any additional filing fees required under 37 CFR §1.16.

Any patent application processing fees under 37 CFR §1.17.

Respectfully submitted,

STEPHEN B. ACKERMAN, REG. NO. 37,761

EXPRESS MAIL CERTIFICATE

Express Mail No. **EV313927335US**

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to Assistant Commissioner of Patents, Alexandria, VA, 22313-1450. Applicant and/or Attorney requests the date of deposit as the Filing Date.

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